## 2SD1450

## Silicon NPN epitaxial planar type

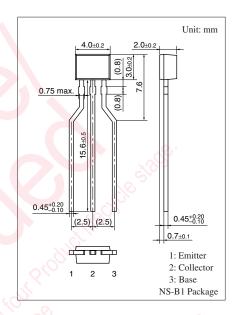
For low-frequency amplification

### ■ Features

- Optimum for high-density mounting
- Allowing supply with the radial taping
- $\bullet$  Low collector-emitter saturation voltage  $V_{\text{CE}(\text{sat})}$

## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	25	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	12	V	
Collector current	$I_{C}$	0.5	A	
Peak collector current	$I_{CP}$	1	A	
Collector power dissipation	P <sub>C</sub>	300	mW	
Junction temperature	$T_{j}$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	



## ■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 10 \mu\text{A}, I_E = 0$	25		10,	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 1 \text{ mA}, I_B = 0$	20	4		V
Emitter-base voltage (Collector open)	$V_{\rm EBO}$	$I_E = 10 \mu\text{A}, I_C = 0$	12	100	0.17	V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 25 \text{ V}, I_{E} = 0$		10	100	nA
Forward current transfer ratio *1	h <sub>FE1</sub> *2	$V_{CE} = 2 \text{ V}, I_{C} = 0.5 \text{ A}$	200	0//	800	_
	h <sub>FE2</sub>	$V_{CE} = 2 \text{ V}, I_{C} = 1 \text{ A}$	60	0.		
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = 500 \text{ mA}, I_B = 20 \text{ mA}$	~ 600	0.13	0.40	V
Base-emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_C = 500 \text{ mA}, I_B = 20 \text{ mA}$			1.2	V
Transition frequency	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		10		pF
(Common base, input open circuited)		The Time				
ON resistance *3	R <sub>on</sub>	113 11/44		0.6		Ω

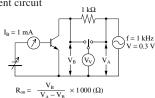
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

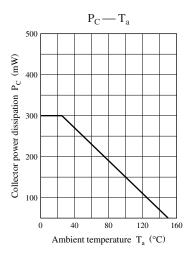
#### 2. \*1: Pulse measurement

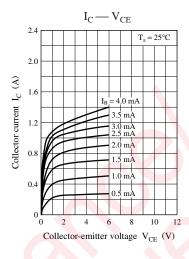
#### \*2: Rank classification

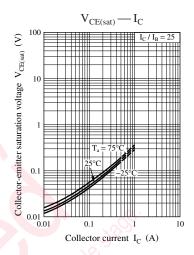
Rank	R	S	Т	No rank
$h_{FE1}$	200 to 350	300 to 500	400 to 800	200 to 800

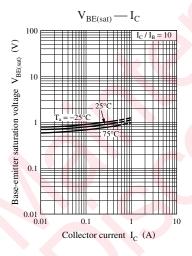
\*3: R<sub>on</sub> Measurement circuit

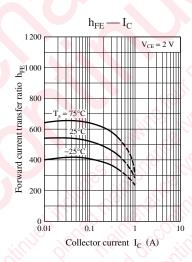


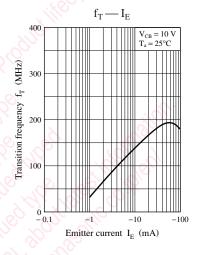


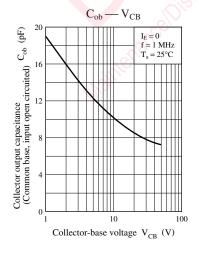


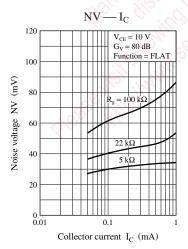












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